

Product Specifications

Customer	Standard
Description	2.13" EPAPER DISPLAY
Model Name	2.13inch e-Paper (G)
Date	2023/05/21
Revision	1.0



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1. Over View

This is a reflective electrophoretic technology display module on an activematrixTFT substrate. The panel is capable of displaying black, white, yellow and redimages depending on the associated lookup table used. The circuitry on the panelincludesan integrated gate and source driver, timing controller, oscillator, DC-DCboostcircuit, and memory to store the frame buffer and lookup tables, and additional circuitry to control VCOM and BORDER settings.

2. Features

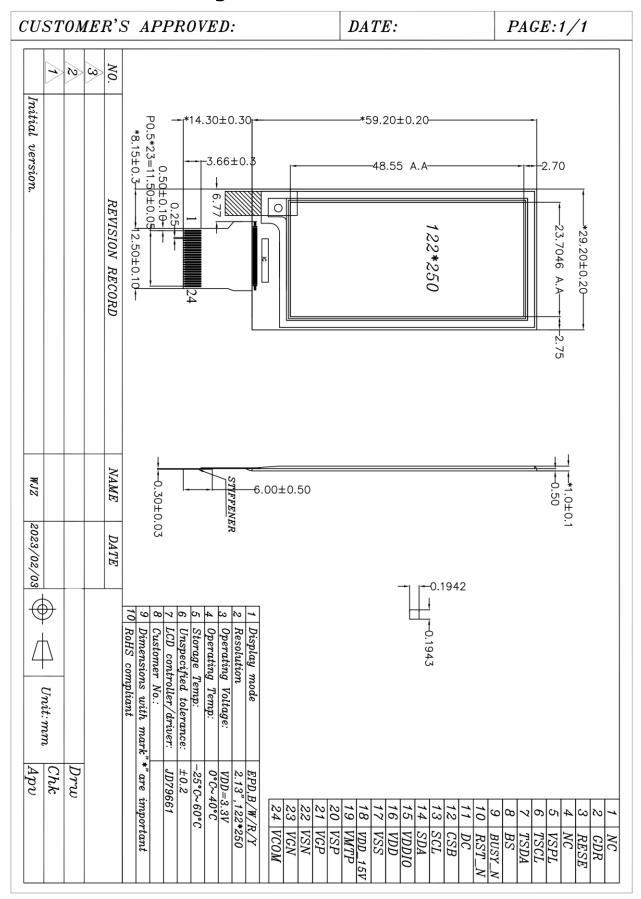
- Highlight Red and Yellow color
- High contrast
- High reflectance
- Ultra wide viewing angle
- Ultra low power consumption
- Pure reflective mode
- Bi-stable display
- Antiglare hard-coated front-surface
- Low current deep sleep mode
- On chip display RAM
- Waveform stored in On-chip OTP
- Serial peripheral interface available
- On-chip oscillator
- On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- I²C signal master interface to read external temperature sensor
- Available in COG package

3. Mechanical Specifications

Parameter	Specifications	Unit	Remark
Screen Size	2.13	Inch	
Display Resolution	122 (H)×250 (V)	Pixel	Dpi:130
Active Area	23.7046×48.55	mm	
Pixel Pitch	0.1942×0.1943	mm	
Pixel Configuration	Rectangle		
Outline Dimension	29.2(H)×59.2(V) ×1.0(D)	mm	
Weight	3.27±0.5	g	



4. Mechanical Drawing of EPD module





5. Input /Output Pin Assignment

No.	Name	I/O	Description	Remark
1	NC		Do not connect with other NC pins	Keep Open
2	GDR	O	This pin is N-MOS gate control.	
3	RESE	P	Current sense input for control loop.	
4	NC	NC	Do not connect with other NC pins	Keep Open
5	VSPL	P	Positive source voltage	
6	TSCL	О	I ² C clock for external temperature sensor (I ² C interface need external pull high resistance.) Must pull high or low if not used.	
7	TSDA	I/O	I ² C data for external temperature sensor (I ² C interface need external pull high resistance.) Must pull high or low if not used.(Default low)	
8	BS	I	Input interface setting.	
9	BUSY_N	О	This pin indicates the driver status.	
10	RST_N	I	Global reset pin. Low reset. (normal pull high)	
11	DC	I	Serial communication Command/Data input	
12	CSB	I	Serial communication chip select.	
13	SCL	I	Serial communication clock input.	
14	SDA	I/O	Serial communication data input.	
15	VDDIO	P	IO voltage supply	
16	VDD	P	Digital/Analog power.	
17	VSS	P	Ground	
18	VDD_15V	P	1.5V voltage input &output	
19	VMTP	P	MTP program power (10.1V)	
20	VSP	P	Positive source voltage	
21	VGP	P	Positive gate voltage	
22	VSN	P	Negative Source driving voltage	
23	VGN	P	Negative gate voltage	
24	VCOM	О	VCOM driving voltage	

Note: I: Input, O: Output, P: Power, D: Dummy, S: Shorted line, M: Mark, PI: Power input, PO: Power output, I/O: Input / Output. PS: Power Setting, C: Capacitor pin.



6. Electrical Characteristics

6.1 Absolute Maximum Rating

Parameter	Symbol	Rating	Unit
	VDD,		
Logic supply voltage	AVDD, VDDIO,	-0.3 to $+6.0$	V
	VDD1,VPP		
Logic Input voltage	VI	-0.3 to VDDIO+0.3	V
Operating Temp range	TOPR	0 to +40	° C
Storage Temp range	TSTG	-25 to +60	° C
Optimal Storage Temp	TSTGo	23±2	° C
Optimal Storage Humidity	HSTGo	55±10	%RH

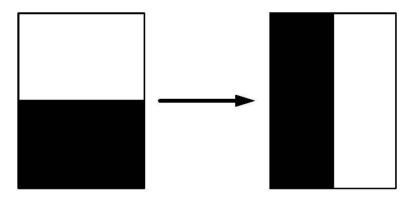
Note: Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposing device to the absolute maximum ratings in a long period of time may degrade the device and affect its reliability.



6.2 Panel DC Characteristics

Parameter	Symbol	Conditions	Applica ble pin	Min.	Тур.	Max	Units
Single ground	V_{SS}	-		-	0	-	V
Logic supply voltage	V_{IO}	-	VIO	2.3	3.3	3.6	V
Core logic voltage	$V_{ m DD}$		VDD	2.3	3.3	3.6	V
High level input voltage	V_{IH}	-	-	$0.7V_{IO}$	-	V_{IO}	V
Low level input voltage	$V_{\rm IL}$	-	-	GND	-	$0.3V_{DD}$	V
High level output voltage	V_{OH}	IOH = 400uA	-	V _{IO} -0.4	-	-	V
Low level output voltage	V_{OL}	IOL = -400uA	-	GND	-	GND +0.4	V
Typical power	P_{TYP}	$V_{CI} = 3.3V$	-	-	9.9	-	mW
Deep sleep mode	P_{STPY}	$V_{CI} = 3.3V$	-	-	0.003	-	mW
Typical operating current	Iopr_V _{CI}	$V_{CI} = 3.3V$	-	-	3.0	-	mA
Image update time	-	25 ℃	-	-	25	-	sec
Stand-by current	Ist_V _{DD}		-	-	1	5	uA

Notes: 1. The typical power is measured with following transition from horizontal 2 scale pattern to vertical 2 scale pattern.



- 2. The deep sleep power is the consumed power when the panel controller is in deep sleep mode.
- 3. The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by Waveshare.



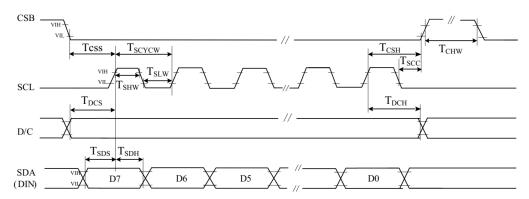
6.3 AC Characteristics

6.3.1 MCU Interface Selection

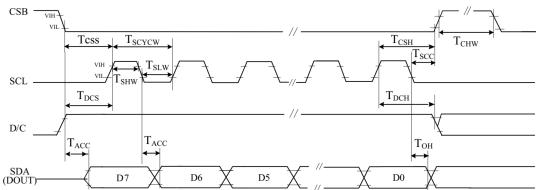
The 3-wire/4-wire serial port as communication interface for all the function and command setting. 3-wire/4-wire engine act as a "slave mode" for all the time, and will not issue any command to the 3-wire/4-wire bus itself.

Under read mode, 3-wire/4-wire engine will return the data during "Data phase". The returned data should be latched at the rising edge of SCL by external controller. Data in the "Hi-Z phase" will be ignored by 3-wire/4-wire engine during write operation, and should be ignored during read operation also. During read operation, external controller should float SDA pin under "Hi-Z phase" and "Data phase".

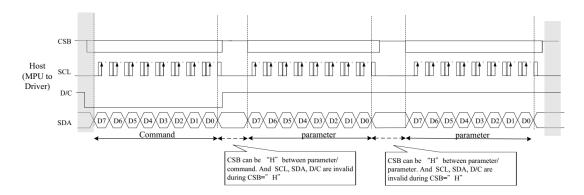
6.3.2 MCU Serial Interface (4-wire SPI)



4 pin serial interface characteristics(write mode)

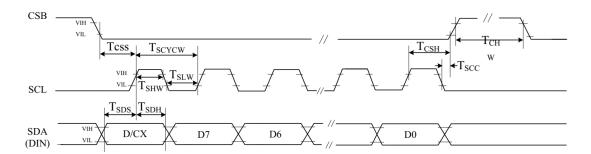


4 pin serial interface characteristics(read mode)

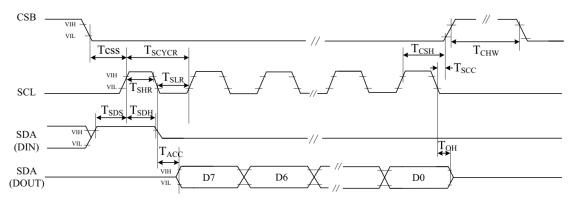




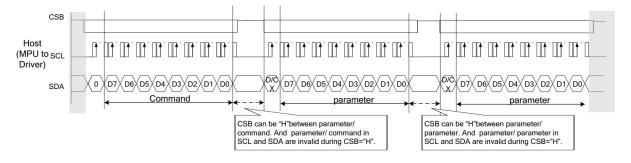
6.3.3 MCU Serial Interface (3-wire SPI)



3 pin serial interface characteristics (write mode)



3 pin serial interface characteristics (read mode)





7. Command Table

Address	command								E	3it		
Address	command	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
		W	0	0	0	0	0	0	0	0	0	00H
R00H	Panel setting (PSR)	W	1	RES[1]	RES[0]	PST_MODE	-	UD	SHL	SHD_N	RST_N	0Fh
		W	1	LUT_EN	-	FOPT	VCMZ	TS_AUTO	TIEG	NORG	VC_LUTZ	09h
		W	0	0	0	0	0	0	0	0	1	01H
		W	1	-	-	-	-	V_MODE	VSC_EN	VDS_EN	VDG_EN	07h
		W	1	-	-	-	-	-	-	VGPN [1]	VGPN [0]	00h
R01H	Power setting (PWR)	W	1	-	VSPL_0[6]	VSPL_0[5]	VSPL_0[4]	VSPL_0[3]	VSPL_0[2]	VSPL_0[1]	VSPL_0[0]	00h
		W	1	-	VSP_1[6]	VSP_1 [5]	VSP_1 [4]	VSP_1 [3]	VSP_1 [2]	VSP_1 [1]	VSP_1 [0]	00h
		W	1	-	VSN_1[6]	VSN_1[5]	VSN_1[4]	VSN_1[3]	VSN_1[2]	VSN_1[1]	VSN_1[0]	00h
		W	1	-	VSPL_1[6]	VSPL_1[5]	VSPL_1[4]	VSPL_1[3]	VSPL_1[2]	VSPL_1[1]	VSPL_1[0]	00h
		W	0	0	0	0	0	0	0	1	0	02H
R02H	Power OFF(POF)	W	1	-	-	-	-	-	-	-	EDSE	00h
		W	0	0	0	0	0	0	0	1	1	03H
	Power off Sequence	W	1		-	T_VDPG	OFF[1:0]		-	T_VDS	OFF[1:0]	00h
R03H	Setting(PFS)	W	1		VGP_LE				VGP I	EXT[3:0]		54
	. ,	W	1		XON_					LEN		44
R04H	Power ON (PON)	W	0	0	0	0	0	0	1	0	0	04H
	1 01101 011 (1 011)	W	0	0	0	0	0	0	1	1	0	06H
		W	1	-	-	_	-					00H
		W	1	-	-		The conting					00h
				-	-		PHA_ON[5:0]					
R06H Booster Soft Start (BTST)	W	1	-		PHA_OFF[5:0]						07h	
	(5101)	W	1	-	-		PHB_ON[5:0]					02h
		W	1	-	-		PHB_OFF[5:0]					07h
		W	1	-	-	PHC_ON[5:0] PHC_OFF[5:0]					02h	
		W	1	-	-			1				07h
R07H	Deep Sleep(DSLP)	W	0	0	0	0	0	0	1	1	1	07H
		W	1	1	0	1	0	0	1	0	1	A5h
R10H	Data Start transmission (DTM)	W	0	0	0	0	1	0	0	0	0	10H
	transmission (DTM)	W	1	#	#	#	#	#	#	#	#	00H
R11H	Data Stop (DSP)	W	0	0	0	0	1	0	0	0	1	11H
		R	1	Data_flag	-	-	-	-	-	-	-	
R12H	Display Refresh	W	0	0	0	0	1	0	0	1	0 AC/DC	12H
	(DRF)	W	1	-	-	-	-	-	-	-	VCOM	00H
R17H	Auto sequence	W	0	0	0	0	1	0	1	1	1	17H
	(AUTO)	W	1	Code[7]	Code[6]	Code[5]	Code[4]	Code[3]	Code[2]	Code[1]	Code[0]	A5h
R30H	PLL control (PLL)	W	0	0	0	1	1	0	0	0	0	30H
	(,	W	1	-	-	-	-	Dyna		FR[2:0]		02h
	Temperature Sensor	W	0	0	1	0	0	0	0	0	0	40H
R40H	Command (TSC)	R	1	D10/TS[7]	D9/TS[7]	D8/TS[6]	D7/TS[5]	D6/TS[4]	D5/TS[3]	D4/TS[2]	D3/TS[1]	
Command (100)	R	1	D2/ TS[9]	D1/TS[8]	D0	-	-	-	-	-		
R41H	Temperature Sensor	W	0	0	1	0	0	0	0	0	1	41H
	Calibration (TSE)	W	1	TSE	-	-	TO[4]	TO[3]	TO[2]	TO[1]	TO0]	00h
		W	0	0	1	0	0	0	0	1	0	42H
R42H	Temperature Sensor	W	1	WATTR[7]	WATTR[6]	WATTR[5]	WATTR[4]	WATTR[3]	WATTR[2]	WATTR[1]	WATTR[0]	00h
117411	Write (TSW)	W	1	WMSB[7]	WMSB[6]	WMSB[5]	WMSB[4]	WMSB[3]	WMSB[2]	WMSB[1]	WMSB[0]	00h
		W	1	WLSB[7]	WLSB[6]	WLSB[5]	WLSB[4]	WLSB[3]	WLSB[2]	WLSB[1]	WLSB[0]	00h
R43H	Temperature Sensor	W	0	0	1	0	0	0	0	1	1	43H



RSSIN VCOM and DATA W		Read (TSR)	l p		T DMODET	L	Lawanes	- Butantii					
No		ricad (1011)	R	1	RMSB[7]	RMSB[6]	RMSB[5]	RMSB[4]	RMSB[3]	RMSB[2]	RMSB[1]	RMSB[0]	
Interval setting (CDI) W					<u> </u>							-	
R61H	R50H												
Resolution Program Revision (LPD) R		9 . ,			 								
Resolution Setting(TRES)	R51H			_			0	1	0	0	0		51H
Resolution setting(TRES)		Detection (Li D)					-	-	-	-	-		
Resolution Setting(TRES)					0	1	1	0	0	0			
Setting(I NES)	Deall	Resolution			-		-	-	-	-		. ,	
Result W	KOIH	setting(TRES)			HRES(7)	HRES(6)	HRES(5)	HRES(4)	HRES(3)	HRES(2)			
R65H Gate/Source Start Setting(GSST)				-			-	-	-	-			
Result					_		-		· · ·			- '	
Reserved				_	0			0	0	1			
REVISION (REV)	DOELL	Gate/Source Start			-			-	-	-			
REVISION (REV)	RooH	Setting(GSST)		-	S_start(7)	S_start(6)	S_start(5)	S_start(4)	S_start(3)	S_start(2)			00h
REVISION (REV)					-	-	-	-	-	-			
REVISION (REV)					<u> </u>								00h
REVISION (REV)													
R80H Auto Measure Vcom (AMV)	R70H	REVISION (REV)											03h
R80H Auto Measure Vcom		. ,						_					
R80H										0	0	1	01h
R81H Vcom Value (VV)	R80H				-						0	0	80 H
R81H Vcom Value (W) R		(AMV)									AMV	AMVE	00h
R82H Vcom_DC Setting register(VDCS)	R81H	Vcom Value (VV)		0	1		0	0	0	0	0	1	81H
Register(VDCS)		` ′						VV[4]	VV[3]	VV[2]	VV[1]	VV[0]	
R83H	R82H			0			0	0	0	0	1	0	82H
R83H Partial Window (PTLW)		register(VDCS)							VDCS[3]	VDCS[2]	VDCS[1]	VDCS[0]	00h
R83H Partial Window (PTLW) W				0	1	0	0	0	0	0	1	1	83H
R83H Partial Window (PTLW)					-	-	-	-	-	-	HRST(9)	HRST(8)	00h
Partial Window (PTLW)				_	HRST(7)	HRST(6)	HRST(5)	HRST(4)	HRST(3)	HRST(2)	0	0	00h
R83H					-		-	-	-	-	HRED(9)	HRED(8)	00h
W	R83H		W	1	HRED(7)	HRED(6)	HRED(5)	HRED(4)	HRED(3)	HRED(2)	0	0	00h
W		(PILVV)			-	-	-	-	-	-	VRST(9)	VRST(8)	00h
W					VRST(7)	VRST(6)	VRST(5)	VRST(4)	VRST(3)	VRST(2)	VRST(1)	VRST(0)	00h
R90H Program W 1 0 0 1 0 0 0 0 0 0					-	-		-	-	-	VRST(9)	VRST(8)	00h
R90H						VRST(6)	VRST(5)	VRST(4)	VRST(3)	VRST(2)	VRST(1)	VRST(0)	00h
R91H		Description	W	1	-	-	-	-	-	-	-	PMOD	00h
R91H Program(APG) W 0 1 0 0 1 0 0 0 1 91H	R90H	mode(PGM)	W	0	1	0	0	1	0	0	0	0	90H
R92H	R91H	Program(APG)			1		0	1	0	0	0	1	91H
R9EH REVISION2 (REV2) R9EH REVISION2 (REV2) R 1 0 0 0 1 1 1 1 1 0 9EH R9FH Read MTP Reserved Bytes(RMRB) R 1 # # # # # # # # # # # # # # # # # #	R92H			0			0	1	0	0	1	0	92H
R9EH REVISION2 (REV2) R 1 0 0 0 0 0 0 0 0 1 01h R9FH Read MTP Reserved Bytes(RMRB) R 1 # # # # # # # # # - RE3H Power saving(PWS) RE4H LVD voltage Select(LVSEL) R 1 0 0 0 0 0 0 0 0 1 1 1 1 1 1 1 1 1 1		(RMTP)			#	#	#	#	#	#	#	#	-
R9FH Read MTP Reserved Bytes(RMRB) R 1 # # # # # # # # # # # # # # # # # #	R9EH	REVISION2 (REV2)		0	1	0	0	1	1	1	1	0	9EH
RE3H Power saving(PWS) R 1 # # # # # # # # #		1.31.0.12 (1.2.72)		1	0	0	0	0	0	0	0	1	01h
RE3H Power saving(PWS) R 1 # # # # # # # # #	R9FH		W	0	1	0	0	1	1	1	1	1	9FH
RE3H Power saving(PWS) W 1 VCOM_W VCOM	110111	Bytes(RMRB)	R	1	#	#	#	#	#	#	#	#	-
RE4H LVD voltage Select(LVSEL) W 1 LVD_SEL LVD_S	RE3H	Power saving/DM/S)	W	0					0	0	1	1	E3H
RE4H	ILOIT	TOWER Saving(FVVS)	w	1					SD_W[3]	SD_W[2]	SD_W[2]	SD_W[0]	00h
Select(LVSEL) W 1 LVD_SEL LVD_	DE4L		W	0					0	1	0		E4H
	NE4FI	Select(LVSEL)	W	1	-	-	-	-	-	-	LVD_SEL [1]	LVD_SEL [0]	03h

R00H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PSR	W	0	0	0	0	0	0	0	0	0	00H
1 st Parameter	W	1	RES[1]	RES[0]	PST_MODE	-	UD	SHL	SHD_N	RST_N	0Fh
2 nd Parameter	W	1	LUT_EN	-	FOPT	VCMZ	TS_AUTO	TIEG	NORG	VC_LUTZ	09h

NOTE: "-" Don't care, can be set to VDD or GND level



Description	-The comman	d defines as :	
	1 st paramete	۵r	
	Bit	Name	Description
			RST N function
	0	RST_N	1: no effect. (default)
	0	_	0: Booster OFF, Register data are set to their default values,
			and Source/Boder/Vcom: floating
			SHD_N function
	1		0 : Booster OFF, register data are kept, and Source/Boder/Vcom are kept 0V or floating.
		_	1 : Booster on. (default)
			SHL function
			0: Shift left; First data=Sn→Sn-1 →→S2→Last data=S1.
	2	SHL	1: Shift right: First data=S1→S2 →→Sn-1→Last data=Sn.
			(default)
			UD function
	3	UD	0:Scan down; First line=Gn→Gn-1 →→G2→Last line=G1.
	3	OD	1:Scan up; First line=G1→G2 →→Gn-1→Last line=Gn.
			(default)
			Power switch operation mode
	5	PST_MODE	0:Power switching time in the period of frame scanning.(default)
		_	Power switching time in the external period before frame scanning.
			Resolution setting
			00: Display resolution is 176x296 (default)
	7-6		01: Display resolution is 128x296
			10: Display resolution is 128x250
			11: Display resolution is 112x204

2 nd paramet	er	
Bit	Name	Description
0	VC_LUTZ	VCOM status function 0 : No effect 1 : After refreshing display,the output of VCOM is set to floating automatically (default)
1	NORG	VCOM status function 0 : No effect (default) 1 : After refreshing display, VCOM is tied to GND before power off
2	TIEG	VGN power off status function O: No effect (default) 1: Power off, VGN will be tied to GND
3	TS_AUTO	Temperature sensing will be activated automatically one time 0 : Before enabling booster, Temperature Sensor will be activated automatically one time. 1 : When RST_N low to high, Temperature Sensor will be activated automatically one time. (default)
4	VCMZ	VCOM status function 0 : No effect (default) 1 : VCOM is always floating
5	FOPT	FOPT function 0: Scan 1 frame after waveform finished(default) 1: No scan after waveform finished and switch the source channel output to Hiz.
7	LUT_EN	LUT selection setting 0 : Using LUT from MTP(default) 1 : Using LUT from register



Priority of VCOM setting: VCMZ > NORG > FOPT > VC_LUTZ

FOPT setting is part of refreshing display.

FOPT: Power off floating.

Notes:

- 1. Non-select gate line keep at VGN for DSP/DRF and AMV
- 2. Dummy source line follow LUTC for DSP/DRF
- 3. When SHD_N become low, DCDC will turn off. Register and SRAM data will keep until VDD turn off.SD output and VCOM will base on previous condition. It may have two condition:0V or floating.
- 4. When RST_N become low, driver will reset. All register will reset to default value. All of the driver's functions will disable. Source/Gate/Border/VCOM will be released to floating

R01H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PWR	W	0	0	0	0	0	0	0	0	1	01h
1 st Parameter	W	1	-	-	-	-	V_MODE	VSC_EN	VDS_EN	VDG_EN	07h
2 nd Parameter	W	1	1	-	-	-	-	-	VGPN [1]	VGPN [0]	00h
3 rd Parameter	W	1	-	VSPL_0 [6:0]					00h		
4 th Parameter	W	1	1	VSP_1 [6:0]						00h	
5 th Parameter	W	1	1	VSN_1 [6:0]						00h	
6 th Parameter	W	1	-			\	/SPL_1 [6:0	0]			00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description

-The command defines as :

1st Parameter:

Bit	Name	Description
0	VDG_EN	Gate power selection. 0 : External gate power from VGP/VGN pins. 1 : Internal DCDC function for generate VGP/VGN. (default)
1	VDS_EN	Source power selection. 0 : External source power from VSP/VSN pins. 1 : Internal regulator function for generate VSP/VSN (default)
2	VSC_EN	Source LV power selection. 0 : External source power from VSPL pins. 1 : Internal regulator function for generate VSPL (default)
3	V_MODE	Source Power switching mode. D: Mode0(default) 1: Mode1

2nd Parameter:

Bit	Name	Description
1-0	VGPN	VGPN Voltage Level. 00: VGP=20 v, VGN=-20v (default) 01: VGP=17 v, VGN=-17v 10: VGP=15 v, VGN=-15v 11: VGP=10 v, VGN=-10v



3rd & 4th & 6th Parameter: Internal VSP_1/VSPL_0/ VSPL_1 power selection

	bit[6:0 0000000 0000001		Voltage(V) 3 3.1	bit [6:0		Voltage(V) 7.1	bit [6:0		Voltage(V)
	0000000 0000001	00h	3	0101001					
	0000001				29h	7.1	1010010	E26	44.0
		01h	2.1				1010010	52h	11.2
		-	3.1	0101010	2Ah	7.2	1010011	53h	11.3
	0000010	02h	3.2	0101011	2Bh	7.3	1010100	54h	11.4
	0000011	03h	3.3	0101100	2Ch	7.4	1010101	55h	11.5
	0000100	04h	3.4	0101101	2Dh	7.5	1010110	56h	11.6
	0000101	05h	3.5	0101110	2Eh	7.6	1010111	57h	11.7
	0000110	06h	3.6	0101111	2Fh	7.7	1011000	58h	11.8
	0000111	07h	3.7	0110000	30h	7.8	1011001	59h	11.9
	0001000	08h	3.8	0110001	31h	7.9	1011010	5Ah	12
	0001001	09h	3.9	0110010	32h	8	1011011	5Bh	12.1
	0001010	0Ah	4	0110011	33h	8.1	1011100	5Ch	12.2
	0001011	0Bh	4.1	0110100	34h	8.2	1011101	5Dh	12.3
	0001100	0Ch	4.2	0110101	35h	8.3	1011110	5Eh	12.4
	0001101	0Dh	4.3	0110110	36h	8.4	1011111	5Fh	12.5
	0001110	0Eh	4.4	0110111	37h	8.5	1100000	60h	12.6
	0001111	0Fh	4.5	0111000	38h	8.6	1100001	61h	12.7
	0010000	10h	4.6	0111001	39h	8.7	1100010	62h	12.8
VOD 4	0010001	11h	4.7	0111010	3Ah	8.8	1100011	63h	12.9
	0010010	12h	4.8	0111011	3Bh	8.9	1100100	64h	13
VSPL_0 & VSPL_1	0010011	13h	4.9	0111100	3Ch	9	1100101	65h	13.1
	0010100	14h	5	0111101	3Dh	9.1	1100110	66h	13.2
	0010101	15h	5.1	0111110	3Eh	9.2	1100111	67h	13.3
	0010110	16h	5.2	0111111	3Fh	9.3	1101000	68h	13.4
	0010111	17h	5.3	1000000	40h	9.4	1101001	69h	13.5
	0011000	18h	5.4	1000001	41h	9.5	1101010	6Ah	13.6
	0011001	19h	5.5	1000010	42h	9.6	1101011	6Bh	13.7
	0011010	1Ah	5.6	1000011	43h	9.7	1101100	6Ch	13.8
	0011011	1Bh	5.7	1000100	44h	9.8	1101101	6Dh	13.9
	0011100	1Ch	5.8	1000101	45h	9.9	1101110	6Eh	14
	0011101	1Dh	5.9	1000110	46h	10	1101111	6Fh	14.1
	0011110	1Eh	6	1000111	47h	10.1	1110000	70h	14.2
	0011111	1Fh	6.1	1001000	48h	10.2	1110001	71h	14.3
	0100000	20h	6.2	1001001	49h	10.3	1110010	72h	14.4
	0100001	21h	6.3	1001010	4Ah	10.4	1110011	73h	14.5
	0100010	22h	6.4	1001011	4Bh	10.5	1110100	74h	14.6
	0100011	23h	6.5	1001100	4Ch	10.6	1110101	75h	14.7
	0100100	24h	6.6	1001101	4Dh	10.7	1110110	76h	14.8
	0100101	25h	6.7	1001110	4Eh	10.8	1110111	77h	14.9
	0100110	26h	6.8	1001111	4Fh	10.9	1111000	78h	15
	0100111	27h	6.9	1010000	50h	11			45
	0101000	28h	7	1010001	51h	11.1	otner		15
١	& _	VSP_1 & VSP_1 & WSPL_0 & WSPL_1 001001 001010 001010 001001 001001	VSP_1	VSP_1 & VSPL_0 & VSPL_1 O01001 CVSPL_1 O010101 CVSPL_1 O010101 CVSPL_1 O010101 CVSPL_1 O01001 CVSPL_1 O010001 CVSPL_1 O01001 CVSPL_1 O01000 CVSPL_1 O01001 C	VSP_1 & 0000111 07h 3.7 0110000 0001001 09h 3.9 0110010 0001011 08h 4.1 0110101 000110 000110 0Ch 4.2 0110101 000111 0Dh 4.3 0110110 000111 0Eh 4.4 0110111 000111 0Fh 4.5 0111000 001000 10h 4.6 0111001 001001 12h 4.8 0111011 001001 12h 4.8 0111011 001010 12h 4.8 0111011 001011 13h 4.9 011110 001011 15h 5.1 011110 001011 15h 5.1 0111110 001011 17h 5.3 100000 001100 18h 5.4 100001 001100 18h 5.4 100001 001101 19h 5.5 100010 001101 19h 5.5 100011 001101 19h 5.5 100011 001101 19h 5.5 100011 001101 11h 5.9 100111 10h 001111 17h 5.8 100111 001111 17h 5.9 100110 001111 17h 5.9 100110 001111 17h 5.9 100110 001111 17h 5.9 100110 001111 17h 5.9 100010 001111 17h 6.1 1001000 010000 20h 6.2 1001001 010001 21h 6.3 100101 010001 22h 6.4 1001011 010011 23h 6.5 1001100 010010 24h 6.6 1001111 010011 25h 6.7 1001110 010011 25h 6.7 1001110 010011 25h 6.7 1001110 010011 25h 6.7 1010000	VSP_1 & VSPL_0 & VSPL_1 O010101 12h 4.8 0111011 32h 001001 12h 4.8 0111011 32h 001010 12h 4.8 0111011 32h 001010 12h 4.8 0111011 32h 001001 12h 4.8 0111011 32h 001010 12h 4.8 0111110 32h 001010 12h 4.8 0111111 37h 001011 13h 4.9 011110 32h 001010 12h 5.1 011110 32h 001011 13h 5.1 011110 32h 001011 13h 5.1 011110 32h 001011 13h 5.1 011111 37h 001111 13h 5.1 011111 37h 001111 13h 5.1 011111 37h 001111 13h 5.1 011111 37h 001011 17h 5.3 100000 40h 001100 18h 5.4 100001 41h 001100 18h 5.4 100001 42h 001101 17h 5.5 100010 42h 001101 17h 5.9 100010 44h 001110 17h 5.9 100010 44h 001110 17h 5.9 100011 45h 001111 17h 6.1 1001000 48h 010000 20h 6.2 1001001 49h 010001 21h 6.3 100101 47h 010011 23h 6.5 100110 47h 010011 23h 6.5 100110 47h 010010 24h 6.6 100110 47h 010010 24h 6.6 1001110 47h 010010 24h 6.6 100111 47h 010011 25h 6.7 1001110 47h 0100111 27h 6.9 1010000 50h	O000111 O7h 3.7 O110000 30h 7.8	O000111 O7h 3.7 O110000 30h 7.8 1011001	O0001111 O7h 3.7 O110000 30h 7.8 1011001 59h



5th Parameter: Internal VSN_1 power selection

Bit	Name				De	scrip	tion			
		Internal VS	N po	wer selection						
		bit[6:0)]	Voltage(V)	bit [6:0)]	Voltage(V)	bit [6:0	0]	Voltage(V)
		0000000	00h	-3	0101001	29h	-7.1	1010010	52h	-11.2
		0000001	01h	-3.1	0101010	2Ah	-7.2	1010011	53h	-11.3
		0000010	02h	-3.2	0101011	2Bh	-7.3	1010100	54h	-11.4
		0000011	03h	-3.3	0101100	2Ch	-7.4	1010101	55h	-11.5
		0000100	04h	-3.4	0101101	2Dh	-7.5	1010110	56h	-11.6
		0000101	05h	-3.5	0101110	2Eh	-7.6	1010111	57h	-11.7
		0000110	06h	-3.6	0101111	2Fh	-7.7	1011000	58h	-11.8
		0000111	07h	-3.7	0110000	30h	-7.8	1011001	59h	-11.9
		0001000	08h	-3.8	0110001	31h	-7.9	1011010	5Ah	-12
		0001001	09h	-3.9	0110010	32h	-8	1011011	5Bh	-12.1
		0001010	0Ah	-4	0110011	33h	-8.1	1011100	5Ch	-12.2
		0001011	0Bh	-4.1	0110100	34h	-8.2	1011101	5Dh	-12.3
		0001100	0Ch	-4.2	0110101	35h	-8.3	1011110	5Eh	-12.4
		0001101	0Dh	-4.3	0110110	36h	-8.4	1011111	5Fh	-12.5
		0001110	0Eh	-4.4	0110111	37h	-8.5	1100000	60h	-12.6
		0001111	0Fh	-4.5	0111000	38h	-8.6	1100001	61h	-12.7
		0010000	10h	-4.6	0111001	39h	-8.7	1100010	62h	-12.8
		0010001	11h	-4.7	0111010	3Ah	-8.8	1100011	63h	-12.9
		0010010	12h	-4.8	0111011	3Bh	-8.9	1100100	64h	-13
	0 VSN_1	0010010	13h	-4.9	0111100	3Ch	-9	1100100	65h	-13.1
6-0		001011	14h	-5	0111101	3Dh	-9.1	1100101	66h	-13.2
		0010101	15h	-5.1	0111110	3Eh	-9.2	1100111	67h	-13.3
		0010101	16h	-5.2	0111111	3Fh	-9.3	1101000	68h	-13.4
		0010111	17h	-5.3	1000000	40h	-9.4	1101000	69h	-13.5
		0011000	18h	-5.4	1000001	41h	-9.5	1101010	6Ah	-13.6
		0011000	19h	-5.5	1000001	4111 42h	-9.6	1101010	6Bh	-13.7
		0011001	1Ah	-5.6	1000010	4211 43h	-9.7	1101011	6Ch	-13.7
		0011010	1Bh	-5.7	1000011	44h	-9.8	1101101	6Dh	-13.9
		0011011	1Ch	-5.7 -5.8	1000100	45h	-9.8	11011101	6Eh	-13.9
		0011101	1Dh	-5.8 -5.9	1000101	46h	-9.9	1101111	6Fh	-14.1
		0011101	1Eh	-6	1000110	47h	-10.1	1110000	70h	-14.1
									71h	
		0011111	1Fh	-6.1	1001000	48h 49h	-10.2 -10.3	1110001		-14.3 -14.4
		0100000	20h	-6.2	1001001			1110010	72h	
		0100001	21h	-6.3	1001010	4Ah	-10.4	1110011	73h	-14.5
			22h	-6.4		4Bh	-10.5	1110100	74h	-14.6
		0100011	23h 24h	-6.5 -6.6	1001100	4Ch 4Dh	-10.6 -10.7	1110101	75h 76h	-14.7 -14.8
		l 						1110110		
		0100101	25h	-6.7	1001110	4Eh	-10.8	1110111	77h	-14.9
		0100110	26h	-6.8	1001111	4Fh	-10.9	1111000	78h	-15
		0100111	27h	-6.9	1010000	50h	-11	other		-15
		0101000	28n	-1	1010001	5111	-7.1			
		0101000	28h	-7	1010001	51h	-7.1			



5th Parameter: Internal VSN_1 power selection

	Name					scrip	tion			
		Internal VS	N po	wer selection	on.					
		bit[6:0)]	Voltage(V)	bit [6:0)]	Voltage(V)	bit [6:0)]	Voltage(V)
		0000000	00h	-3	0101001	29h	-7.1	1010010	52h	-11.2
		0000001	01h	-3.1	0101010	2Ah	-7.2	1010011	53h	-11.3
		0000010	02h	-3.2	0101011	2Bh	-7.3	1010100	54h	-11.4
		0000011	03h	-3.3	0101100	2Ch	-7.4	1010101	55h	-11.5
		0000100	04h	-3.4	0101101	2Dh	-7.5	1010110	56h	-11.6
		0000101	05h	-3.5	0101110	2Eh	-7.6	1010111	57h	-11.7
		0000110	06h	-3.6	0101111	2Fh	-7.7	1011000	58h	-11.8
		0000111	07h	-3.7	0110000	30h	-7.8	1011001	59h	-11.9
		0001000	08h	-3.8	0110001	31h	-7.9	1011010	5Ah	-12
		0001001	09h	-3.9	0110010	32h	-8	1011011	5Bh	-12.1
		0001010	0Ah	-4	0110011	33h	-8.1	1011100	5Ch	-12.2
		0001011	0Bh	-4.1	0110100	34h	-8.2	1011101	5Dh	-12.3
		0001100	0Ch	-4.2	0110101	35h	-8.3	1011110	5Eh	-12.4
		0001101	0Dh	-4.3	0110110	36h	-8.4	1011111	5Fh	-12.5
		0001110	0Eh	-4.4	0110111	37h	-8.5	1100000	60h	-12.6
		0001111	0Fh	-4.5	0111000	38h	-8.6	1100001	61h	-12.7
		0010000	10h	-4.6	0111001	39h	-8.7	1100010	62h	-12.8
		0010001	11h	-4.7	0111010	3Ah	-8.8	1100011	63h	-12.9
		0010010	12h	-4.8	0111011	3Bh	-8.9	1100100	64h	-13
6-0 VSN_1	0010011	13h	-4.9	0111100	3Ch	-9	1100101	65h	-13.1	
	0010100	14h	-5	0111101	3Dh	-9.1	1100110	66h	-13.2	
	0010101	15h	-5.1	0111110	3Eh	-9.2	1100111	67h	-13.3	
		0010110	16h	-5.2	0111111	3Fh	-9.3	1101000	68h	-13.4
		0010111	17h	-5.3	1000000	40h	-9.4	1101001	69h	-13.5
		0011000	18h	-5.4	1000001	41h	-9.5	1101010	6Ah	-13.6
		0011001	19h	-5.5	1000010	42h	-9.6	1101011	6Bh	-13.7
		0011010	1Ah	-5.6	1000011	43h	-9.7	1101100	6Ch	-13.8
		0011011	1Bh	-5.7	1000100	44h	-9.8	1101101	6Dh	-13.9
		0011100	1Ch	-5.8	1000101	45h	-9.9	1101110	6Eh	-14
		0011101	1Dh	-5.9	1000110	46h	-10	1101111	6Fh	-14.1
		0011110	1Eh	-6	1000111	47h	-10.1	1110000	70h	-14.2
		0011111	1Fh	-6.1	1001000	48h	-10.2	1110001	71h	-14.3
		0100000	20h	-6.2	1001001	49h	-10.3	1110010	72h	-14.4
		0100001	21h	-6.3	1001010	4Ah	-10.4	1110011	73h	-14.5
		0100010	22h	-6.4	1001011	4Bh	-10.5	1110100	74h	-14.6
		0100011	23h	-6.5	1001100	4Ch	-10.6	1110101	75h	-14.7
		0100100	24h	-6.6	1001101	4Dh		1110110	76h	-14.8
		0100101	25h	-6.7	1001110	4Eh	-10.8	1110111	77h	-14.9
		0100110	26h	-6.8	1001111	4Fh	-10.9	1111000	78h	-15
		0100111	27h	-6.9	1010000	50h	-11	other		-15
		0101000	28h	-7	1010001	51h	-7.1			



Notes:

- 1. VSP 0/VSN 0 voltage output is ±15 V fixed value.
- 2. When switching Mode0 or Mode1, the voltage output is: Mode0: VSP_0(+15) / VSN_0 (-15) / VSPL_0 (+3~+15) Mode1: VSP_1(+3~+15) / VSN_1(-3~-15) / VSPL_1(+3~+15)

	Mode0	Mode1
VSP	VSP_0(+15)	VSP_1(+3~+15)
VSN	VSN_0(-15)	VSN_1(-3~-15)
VSPL	VSPL_0(+3~+15)	VSPL_1(+3~+15)

3. If gate voltage is set to +/-15v, +/-10v, IC will auto correct source voltage as follows I. VGP- VSP_0 / VSPL_0 / VSP_1 / VSPL_1 >= 2v II. $VGN-VSN_0 / VSN_1 >= -2v$ For example:

	symbol	Voltage setting	Real Voltage		
	VGP	10v	+10v		
	VGN	10v	-10v		
	VSP_0	+15v	+8v		
	VSN_0	-15v	-8v		
Valtage	VSP_1	+5v	+5v		
Voltage	VSN_1	-5v	-5v		
	VSPL	+15v	+8v		
	VCOMH	+15v+(-2v)	+8v +(-2v)		
	VCOML	-15v+(-2v)	-8v +(-2v)		
	VCOMDC	-2v	-2v		

4. Voltage setting limit: VSP_0 ≥ VSPL_0 , VSP_1 ≥ VSPL_1

Restriction

R02H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
POF	W	0	0	0	0	0	0	0	1	0	02H
1 st Parameter	W	0	-	-	-	-	-	-	-	EDSE	00

NOTE: "-" Don't care, can be set to VDD or GND level

Description

-The command defines as :

- After power off command, driver will power off base on power off sequence.
 After power off command, BUSY_N signal will drop from high to low. When finish the power off sequence, BUSY N singal will rise from low to high.
- Power off command will turn off charge pump, T-con, source driver, gate driver, VCOM, temperature sensor, but register and SRAM data will keep until VDD off.
- SD output and VCOM will base on previous condition. It may have two conditions: 0v or floating.

1st parameter

1 paramon	parameter							
Bit	Name	Description						
		EPD Discharge Trigger						
0	EDSE	0 : Disable EPD discharge (default)						
		1 : Enable EPD discharge						

Restriction This command only active when BUSY_N = "1".

R03H				Bit								
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
PFS	W	0	0	0	0	0	0	0	1	1	03H	
1 st Parameter	W	1		-	T_VDPG_OFF [1:0]		-		T_VDS_OFF [1:0]		00h	
2 nd Parameter	W	1		VGP_	LEN[3:0]	EN[3:0]			VGP_EXT[3:0]			
3 rd Parameter	W	1		XON_	DLY[3:0]			XON_L	EN[3:0]		44h	

NOTE: "-" Don't care, can be set to VDD or GND level



Description

-The command defines as :

1st Parameter:

Bit	Name	Description
1-0	T_VDS_OFF	Power off sequence of VSP /VSN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms
5-4	T_VDPG_OFF	Power off sequence of VGP and VGN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms

2nd Parameter

Bit	Name	Description
1-0	VGP_EXT	VGP extension time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0010: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0110: 3500 ms 1000: 4000 ms 1001: 4500 ms 1011: 5500 ms 1010: 5000 ms
7-4	VGP_LEN	1101: 6500 ms When power off, the length of time VGP stay 10V 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0010: 1500 ms 0010: 2000 ms 0100: 2000 ms 0101: 2500 ms (default) 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms 1011: 5500 ms

	1100: 6000 ms 1101: 6500 ms

3rd Parameter:

Bit	Name	Description
3-0	XON_LEN	XON enable time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1010: 5000 ms 1011: 5500 ms



	7-4	XON_DLY	XON delay time 0000: 0 ms 0001: 500 ms 0001: 1000 ms 0010: 1000 ms 0010: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0110: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms 1010: 5000 ms
Restriction			

R04H		Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
PON	W	0	0	0	0	0	0	1	0	0	04H	

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as :
	After power on command, driver will power on base on power on sequence. After power on command, BUSY_N signal will drop from high to low. When finishing the power on sequence(base on PWR command), BUSY_N signal will rise from low to high.
Restriction	This command only active when BUSY_N = "1".

R06H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
BTST	W	0	0	0	0	0	0	1	1	0	06H
1 st Parameter	W	1	-	-	-	-	PHB_S	FT [1:0]	PHA_S	FT [1:0]	00h
2 nd Parameter	W	1	-	-		PHA_ON [5:0]					02h
3 rd Parameter	W	1	-	-			PHA_OF	F [5:0]			07h
4 th Parameter	W	1	-	-			PHB_O	N [5:0]			02h
5 th Parameter	W	1	-	-		PHB_OFF [5:0]					07h
6 th Parameter	W	1	-	-	PHC_ON [5:0]					02h	
7 th Parameter	W	1	-	-			PHC_OF	F [5:0]			07h

-The command	define a	as fol	lows:
1st Parameter:			

Bit	Name	Description
1-0	PHA_SFT	Soft start period of phase A: 00: 10mS (default) 01: 20mS 10: 30mS 11: 40mS
3-2	PHB_SFT	Soft start period of phase B: 00: 10mS (default) 01: 20mS 10: 30mS 11: 40mS

		Bit[5:0]	Description	Bit[5:0]	Description	Bit[5:0]	Description
		000000	strength1	010110	strength23	101100	strength45
	[000001	strength2	010111	strength24	101101	strength46
		000010	strength3	011000	strength25	101110	strength47
	[000011	strength4	011001	strength26	101111	strength48
Description	[000100	strength5	011010	strength27	110000	strength49
	[000101	strength6	011011	strength28	110001	strength50
	[000110	strength7	011100	strength29	110010	strength51
	[000111	strength8	011101	strength30	110011	strength52
	[001000	strength9	011110	strength31	110100	strength53
	Driving	001001		strength32	110101	strength54	
	strength of PHA ON &	001010	strength11	100000	strength33	110110	strength55
	PHB ON &	001011	strength12	100001	strength34	110111	strength56
	PHC_ON	001100	strength13	100010	strength35	111000	strength57
		001101	strength14	100011	strength36	111001	strength58
	[001110	strength15	100100	strength37	111010	strength59
	[001111	strength16	100101	strength38	111011	strength60
	[010000	strength17	100110	strength39	111100	strength61
	[010001	strength18	100111	strength40	111101	strength62
		010010	strength19	101000	strength41	111110	strength63
		010011	strength20	101001	strength42	111111	strength64
		010100	strength21	101010	strength43		
		010101	strength22	101011	strength44		



Description		Bit[5:0]	Description	Bit[5:0]	Description	Bit[5:0]	Description
		000000	Period1	010110	Period23	101100	Period45
		000001	Period2	010111	Period24	101101	Period46
	[000010	Period3	011000	Period25	101110	Period47
	[000011	Period4	011001	Period26	101111	Period48
	Ī	000100	Period5	011010	Period27	110000	Period49
	Ī	000101	Period6	011011	Period28	110001	Period50
	Ī	000110	Period7	011100	Period29	110010	Period51
		000111	Period8	011101	Period30	110011	Period52
	Minimum	001000	Period9	011110	Period31	110100	Period53
	OFF time setting of	001001	Period10	011111	Period32	110101	Period54
	PHA OFF	001010	Period11	100000	Period33	110110	Period55
	<u>~</u>	001011	Period12	100001	Period34	110111	Period56
F	PHB_OFF	001100	Period13	100010	Period35	Period35 111000 P	Period57
	PHC OFF	001101	Period14	100011	Period36	111001	Period58
11.	110_011	001110	Period15	100100	Period37	111010	Period59
	[001111 Period16	Period16	100101	Period38	111011	Period60
		010000	Period17	100110 Period39 111	111100	Period61	
	Ī	010001	Period18	100111	Period40	111101	Period62
	Ī	010010	Period19	101000	Period41	111110	Period63
	Ī	010011	Period20	101001	Period42	111111	Period64
	Ī	010100	010100 Period21 101010	Period43			
	Ī	010101	Period22	101011	Period44		
-							•
Restriction							

R07H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
DSLP	W	0	0	0	0	0	0	1	1	1

0

NOTE: "-" Don't care, can be set to VDD or GND level

W

1st Parameter

Description The command define as follows:

After this command is transmitted, the chip would enter the deep-sleep mode to save power.

0

0

Code 07H

A5h

The deep sleep mode would return to standby by hardware reset.

The only one parameter is a check code, the command would be excited if check code = 0xA5.

Restriction This command only active when BUSY_N = "1".

R10H		Bit											
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code		
DTM	W	0	0	0	0	1	0	0	0	0	10H		
2 bit mode	W	1											
1 st Parameter	W	1	Pix	el1	Pix	el2	Pix	cel3	Pixel4		00h		
:	w	4		:		:		:		:	00h		
:	VV	'		:		:		:		:	OOH		
M th Parameter	W	1	Pixel	(n-3)	Pixel(n-2)		Pixe	Pixel(n-1)		el(n)	00h		

NOTE: "-" Don't care, can be set to VDD or GND level

Description The command define as follows:

The register is indicates that user start to transmit data, then write to SRAM. While data transmission complete, user must send command 12H. Then chip will start to send data/VCOM for panel.

Pixel [1~n][1:0]: 2-bit/pixel

L	r ixer [1 Hij[1.0	J. Z-DIUPINGI			
l	Image Data	DDX=	1(default)	DD	X=0
	Pixel[1:0]	Gray level select	IP output LUT select	Gray level select	IP output LUT select
	00b	Gray0	ogray00	Gray3	ogray03
	01b	Gray1	ogray01	Gray2	ogray02
	10b	Gray2	ogray02	Gray1	ogray01
	11b	Gray3	ogray03	Gray0	ogray00



Data mapping example:

When DDX=1,Pixel[1:0]=01 ->Gray level select=Gray1,follow LUT data output from IP output port"ogray01".

When DDX=0,Pixel[1:0]=11 ->Gray level select=Gray0,follow LUT data output from IP output port"ogray00"

Restriction

R11H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DSP	W	0	0	0	0	1	0	0	0	1	11H
1 st Parameter	R	1	Data_flag	-	-	-	-	-	-	-	-

NOTE: "-" Don't care, can be set to VDD or GND level

Description

- -The command defines as :
- While finished the data transmitting, user must send this command to driver and read Data_flag information.

1st Parameter:

Bit	Name	Description
7	Data_flag	O: Driver didn't receive all the data. Driver has already received all of the one frame data.

After "Data Start" (10h) or "Data Stop" (11h) commands and when data_flag=1, BUSY_N signal will become "0" and the refreshing of panel starts.

Restriction This command only actives when BUSY_N = "1".

R12H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DRF	W	0	0	0	0	1	0	0	1	0	12H
1 st Parameter	w	1	-	-	-	-	-	-	-	AC/DC VCOM	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description -The command define

While users send this command, driver will refresh display (data/VCOM) base on SRAM data and LUT.

AC/DC VCOM:

0: AC VCOM, VCOM will follow LUTC when updating image. (default)

1: DC VCOM, VCOM will always be VCOMDC when updating image

After display refresh command, BUSY_N signal will become "0"

Restriction This command only actives when BUSY_N = "1"

R17H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
Auto Sequence	W	0	0	0	0	1	0	1	1	1	17H
1 st Parameter	W	1	Code[7]	Code[6]	Code[5]	Code[4]	Code[3]	Code[2]	Code[1]	Code[0]	A5h

Description

The command can enable the internal sequence to execute several commands continuously. The successive execution can minimize idle time to avoid unnecessary power consumption and reduce the complexity of host's control procedure. The sequence contains several operations, including PON, DRF, POF, DSLP.

AUTO $(0x17) + Code(0xA5) = (PON \rightarrow DRF \rightarrow POF)$

 $\mathsf{AUTO}\ (0\mathsf{x}17) + \mathsf{Code}(0\mathsf{x}\mathsf{A7}) = (\mathsf{PON} {\rightarrow} \mathsf{DRF} {\rightarrow} \mathsf{POF} {\rightarrow} \mathsf{DSLP})$

Restriction This command only actives when BUSY_N = "1".

R30H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PLL	W	0	0	0	1	1	0	0	0	0	30H
1 st Parameter	W	1	-	-	-	-	Dyna	FR[2]	FR[1]	FR[0]	02h

NOTE: "-" Don't care, can be set to VDD or GND level



Description -The command defines as: The command controls the PLL clock frequency. The PLL structure must support the following frame rates: bit3 Dynamic frame rate 0 1 Enable Frame rate FR[2:0] 12.5 Hz 25 Hz 001 010 50 Hz(default) 011 65 Hz 100 75 Hz 101 85 Hz 110 100 Hz 111 120 Hz remark -Horizental hsync H active de 231 clk -Vertical vsync V active de 351 lines Restriction

R40H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSC	W	0	0	1	0	0	0	0	0	0	40H
1 st Parameter	R	1	D10/TS[7]	D9/TS[6]	D8/TS[5]	D7/TS[4]	D6/TS[3]	D5/TS[2]	D4/TS[1]	D3/TS[0]	-
2 nd Parameter	R	1	D2/ TS[9]	D1/ TS[8]	D0	-	-	-	-	-	-

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defi This command indic If R41H(TSE) bit7 s If R41H(TSE) bit7 s	cates the t et to 0, thi	emperature value. s command reads in			
	SPI TSC command		TSC parameters			
	CSB					
	sctIMMML					
	П	П	TSC			
	SDA ————————————————————————————————————		value			
	BUSY_N					
	TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)
	11100111	-25	00000000	0	00011001	25
	11101000	-24	0000001	1	00011010	26
	11101001	-23	00000010	2	00011011	27
	11101010	-22	00000011	3	00011100	28
	11101011	-21	00000100	4	00011101	29
	11101100	-20	00000101	5	00011110	30
	11101101	-19	00000110	6	00011111	31
	11101110	-18	00000111	7	00100000	32
	11101111	-17	00001000	8	00100001	33
	11110000	-16	00001001	9	00100010	34



11110001	-15	00001010	10	00100011	35
11110010	-14	00001011	11	00100100	36
11110011	-13	00001100	12	00100101	37
11110100	-12	00001101	13	00100110	38
11110101	-11	00001110	14	00100111	39
11110110	-10	00001111	15	00101000	40
11110111	-9	00010000	16	00101001	41
11111000	-8	00010001	17	00101010	42
11111001	-7	00010010	18	00101011	43
11111010	-6	00010011	19	00101100	44
11111011	-5	00010100	20	00101101	45
11111100	-4	00010101	21	00101110	46
11111101	-3	00010110	22	00101111	47
11111110	-2	00010111	23	00110000	48
11111111	-1	00011000	24	00110001	49

TS[9:8]	T (°C)
00	+0
01	+0.25
10	+0.5
11	+0.75

Restriction

This command only actives when BUSY_N = "1".

R41H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSE	W	0	0	1	0	0	0	0	0	1	41H
1 st Parameter	W	1	TSE	-	-	TO[4]	TO[3]	TO[2]	TO[1]	TO[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description | -The command defines as:

This command indicates the driver IC temperature sensor enable and calibration function.

Reserve one temperature offset TO[3:0] for calibration 1. TO[3]: mean '+' or '-' , while 0 is '+' ; 1 is '-' 2. TO[2:0]: mean temperature offset value

Bit	Name	Description
3-0	TO[3:0]	Temperature level: 0000: +0°C (default) 0001: +0.5°C 0010: +1°C 0011: +1.5°C 0100: +2°C 0101: +2.5°C 0110: +3°C 0111: +3.5°C 1000: -4°C 1001: -3.5°C 1010: -3°C 1110: -2.5°C 1110: -1.5°C 1111: -0.5°C
4	TO[4]	0: +0.0°C (default) 1: +0.25°C
7	TSE	Internal temperature sensor enable 0: Internal temperature sensor enable.(default) 1: Internal temperature sensor disable, using external temperature sensor.

Restriction This command only actives after R04H(PON)

R42H		Bit													
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code				
TSW	W	0	0	1	0	0	0	0	1	0	42H				
1 st Parameter	W	1	WATTR[7]	WATTR[6]	WATTR[5]	WATTR[4]	WATTR[3]	WATTR[2]	WATTR[1]	WATTR[0]	00h				
2 nd Parameter	W	1	WMSB[7]	WMSB[6]	WMSB[5]	WMSB[4]	WMSB[3]	WMSB[2]	WMSB[1]	WMSB[0]	00h				
3 rd Parameter	W	1	WLSB[7]	WLSB[6]	WLSB[5]	WLSB[4]	WLSB[3]	WLSB[2]	WLSB[1]	WLSB[0]	00h				

NOTE: "-" Don't care, can be set to VDD or GND level



Description	-The con	nmand defines a	as:						
	This cor	nmand writes tl	he temperature.						
	1 st Para	meter:							
	Bit	Name	Description						
	2-0	WATTR[2:0]	Pointer setting						
	5-3	WATTR[5:3]	User-defined address bits (A2, A1, A0)						
			I2C Write Byte Number						
			00: 1 byte (head byte only)						
	7-6	WATTR[7:6]	01: 2 bytes (head byte + pointer)						
			10: 3 bytes (head byte + pointer + 1st parameter)						
			11: 4 bytes (head byte + pointer + 1st parameter + 2nd parameter)						
	2 nd Para	meter:							
	Bit	Name	Description						
	7-0	WMSB[7:0]	MSByte of write-data to external temperature sensor						
	3 nd Para	meter:							
	Bit	Name	Description						
	7-0	WLSB[7:0]	LSByte of write-data to external temperature sensor						
Restriction	This con	nmand only act	tives after R04H(PON)						

R43H		Bit												
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code			
TSR	W	0	0	1	0	0	0	0	1	1	43H			
1 st Parameter	R	1	RMSB[7]	RMSB[6]	RMSB[5]	RMSB[4]	RMSB[3]	RMSB[2]	RMSB[1]	RMSB[0]	-			
2 nd Parameter	R	1	RLSB[7]	RLSB[6]	RLSB[5]	RLSB[4]	RLSB[3]	RLSB[2]	RLSB[1]	RLSB[0]	-			

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The comr	nand defines as	S:
	This comr		e temperature sensed by the temperature sensor.
	Bit	Name	Description
	7-0	RMSB[7:0]	MSByte of read-data from external temperature sensor
	2 nd Param		
	Bit	Name	Description
	7-0	RLSB[7:0]	LSByte of write-data from external temperature sensor
	SPI	TSR command	TSR parameters
	CSB		
	SCL —		
	SDA —		TSR value
	BUSY_N		
Restriction	This comr	mand only activ	ves after R04H(PON)

R50H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
CDI	W	0	0	1	0	1	0	0	0	0	50H
1 st Parameter	W	1	VBD[2]	VBD[1]	VBD [0]	DDX	CDI[3]	CDI[2]	CDI[1]	CDI[0]	97h

NOTE: "-" Don't care, can be set to VDD or GND level



Description -The command defines as: This command can set 2 kinds of parameters, 1.VCOM to data output interval(CDI) CDI[3:0]: This command indicates the interval of VCOM and data output. When setting the vertical back porch, the total blanking will be keep (55hsync) Name Description Vcom and data interval 0000: 17 hsync 0001:16 hsync 0010:15 hsync 0010:13 hsync 0011:14 hsync 0100:13 hsync 0101:12 hsync 0110:11 hsync 0111:10 hsync(default) 1000:9 hsync 1001:8 hsync CDI[3:0] 3-0 1010:7 hsync 1011:6 hsync 1100:5 hsync 1101:4 hsync 1110:3 hsync 1111:2 hsync Internal VCOM need to be ready before source data outpu Internal Internal VCOM output location (fixed) Frame N+1 VCOM VCOM Frame N VCOM Source data Frame N data Output CDI setting 55 hsync-CDI setting (fixed)

VBD[2:0]: Border data selection. (from LUT output by IP port border_w[1:0])

This register will make boarder pin output being mapped to a certain gray scale.

Bit 4	Bit7-5	Description	IP setting for Border LUT
DDX	VBD[2:0]	Gray level	select
	000	Floating	N/A
	001	Gray3	border_buf=011
0	010	Gray2	border_buf=010
	011	Gray1	border_buf=001
	100	Gray0	border_buf=000
	000	Gray0	border_buf=000
	001	Gray1	border_buf=001
1 (default)	010	Gray2	border_buf=010
	011	Gray3	border_buf=011
	100	Floating	N/A

Border output voltage level: The level selection is based on mapping LUT data.

Ex: Gray 1 waveform is mapping to 15V,without VCOM offset, the real output on Boarder pin shall be 15V.

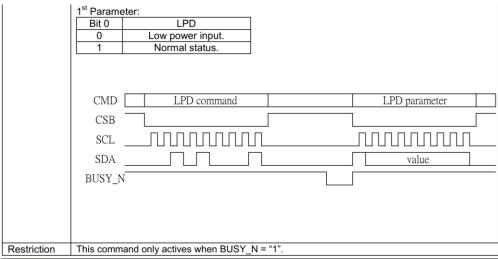
Boarder output will follow FOPT definition being defined in R00h.

R51H	Bit											
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
LPD	W	0	0	1	0	1	0	0	0	1	51H	
1 st Parameter	R	1	-	-	-	-	-	-	-	LPD		

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as: This command indicates the input power condition. Host can read this data to understand the battery's condition.
	When LPD="1", system input power is normal. When LPD="0", system input power is lower (VDD<2.5v, which could be select in RE4H (LVSEL)).





R61H		Bit												
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code			
TRES	W	0	0	1	1	0	0	0	0	1	61H			
1 st Parameter	W	1		-	-	-	-	-	HRES(9)	HRES(8)	00h			
2 nd Parameter	W	1	HRES(7)	HRES(6)	HRES(5)	HRES(4)	HRES(3)	HRES(2)	0	0	00h			
3 rd Parameter	W	1	-	-	-	-	-	-	VRES(9)	VRES(8)	00h			
4 th Parameter	W	1	VRES(7)	VRES(6)	VRES(5)	VRES(4)	VRES(3)	VRES(2)	VRES(1)	VRES(0)	00h			

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: When using register: Horizontal display resolution(source) = HRES Vertical display resolution(gate) = VRES							
	Note:							
	No matter HRES[9:8],HRES[1:0],VRST[9] value being filled, it's always be 00b.							
	Channel disable calculation: GD: First G active = G0; LAST active GD= first active +VRES[9:0] -1 SD: First active channel: =S0; LAST active SD= first active +HRES[9:2]*4-1							
	EX :176X296 GD: First G active = G0 LAST active GD= 0+296-1= 295; (G295) SD : First active SD=0+44*4 1=475; (S175)							
	LAST active SD=0+44*4-1=175; (S175) Note: Only supports source 176.ch for source 160ch. above							
Restriction	Horizontal resolution should be 4-multiple.							

R65H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
GSST	W	0	0	1	1	0	0	1	0	1	65H
1 st Parameter	W	1	-	-	-	-	-	-	S_start[9]	S_start[8]	00h
2 nd Parameter	W	1	S_start[7]	S_start[6]	S_start[5]	S_start[4]	S_start[3]	S_start[2]	0	0	00h
3 rd Parameter	W	1	-	-	-	-	-	-	G_start[9]	G_start[8]	00h
4 th Parameter	W	1	G_start[7]	G_start[6]	G_start[6]	G_start[4]	G_start[3]	G_start[2]	G_start[1]	G_start[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: Note: No matter S_start[9:8], S_start [1:0],VRST[9] value being filled, it's always be 00b.
Description	1.S_Start [7:0] describe which source output line is the first date line 2.G_Start[8:0] describe which gate line is the first scan line
Restriction	S_Start should be the multiple of 4



R70H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
REV	W	0	0	1	1	1	0	0	0	0	70H
1 st Parameter	R	1	0	0	0	0	0	0	1	1	03h
2 nd Parameter	R	1	0	0	0	0	0	0	1	0	02h
3 rd Parameter	R	1	0	0	0	0	0	0	0	1	01h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The commar	nd defines as:	
	1 st & 2 nd & 3 ^r	^d Parameter:	
	Bit	Description	
	7-0	CHIP_REV	
Restriction			

R80H	Bit											
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
AMV	W	0	1	0	0	0	0	0	0	0	80H	
1 st Parameter	W	1	P[1]	P[0]	AMVT[1]	AMVT[0]	XON	AMVS	AMV	AMVE	00h	

NOTE: "-" Don't care, can be set to VDD or GND level

Description		mand defines as nand indicates t	s: the IC status. Host can read this data to understand the IC status.
	1 st Parame		
	Bit	Name	Description
	0	AMVE	AMVE: Auto Measure Vcom Setting 0: Auto measure VCOM disable (default) 1: Auto measure VCOM enable
	1	AMV	AMV: Analog signal 0:Get Vcom value from R81h(default) 1:Get Vcom value in analog signal
	2	AMVS	AMVS: setting for Source output of AMV 0: Source output 0V during Auto Measure VCOM period. (default) 1: Source output VSPL 0 during Auto Measure VCOM period.
	3	XON	XON: setting for all Gate ON of AMV 0: Gate normally scan during Auto Measure VCOM period. (default) 1: All Gate ON during Auto Measure VCOM period.
	5-4	AMVT[1:0]	The sensing time of VCOM detection 00: 5s (default) 01: 10s 10: 15s 11: 20s
	7-6	P[1:0]	The sensing points of sampling time 00: 2 (default) 01: 4 10: 8 11: 16 Sampling time = the last quarter of sensing time (T) VCOM = average of N points. N=2,4,8,16
	Source volta		Vcom controlled by sensing mode ✓
	BUSY_N		The last quarter of sensing time
			Vcom Sensing Average of N point. N=2,4,8,16
Restriction	This comm	and only actives	s when BUSY_N = "1".



R81H		Bit											
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code		
VV	W	0	1	0	0	0	0	0	0	1	81H		
1 st Parameter	R	1	-	VV[6]	VV[5]	VV[4]	VV[3]	VV[2]	VV[1]	VV[0]			

NOTE: "-" Don't care, can be set to VDD or GND level

escription		mmand defines nmand could ge		value														
	1 st Parar	meter:																
	Bit	Name				Des	scription											
			VCOM value															
			VCOM[6:0]	Voltage(V)	VCOM[6	6:0]	Voltage(V)	VCOM[6:0]	Voltage(V)								
			0000000 00h	0	0011100	1Ch	-1.4	0111000	38h	-2.8								
			0000001 01h	-0.05	0011101	1Dh	-1.45	0111001	39h	-2.85								
			0000010 02h	-0.1	0011110	1Eh	-1.5	0111010	3Ah	-2.9								
			0000011 03h	-0.15	0011111	1Fh	-1.55	0111011	3Bh	-2.95								
			0000100 04h	-0.2	0100000	20h	-1.6	0111100	3Ch	-3								
			0000101 05h	-0.25	0100001	21h	-1.65	0111101	3Dh	-3.05								
			0000110 06h	-0.3	0100010	22h	-1.7	0111110	3Eh	-3.1								
			0000111 07h	-0.35	0100011	23h	-1.75	0111111	3Fh	-3.15								
			0001000 08h	-0.4	0100100	24h	-1.8	1000000	40h	-3.2								
			0001001 09h	-0.45	0100101	25h	-1.85	1000001	41h	-3.25								
			0001010 0Ah	-0.5	0100110	26h	-1.9	1000010	42h	-3.3								
			0001011 0Bh	-0.55	0100111	27h	-1.95	1000011	43h	-3.35								
		VV[6:0]	0001100 0Ch	-0.6	0101000	28h	-2	1000100	44h	-3.4								
	6-0		VV[6:0]	VV[6:0]	VV[6:0]	VV[6:0]	VV[6:0]	0001101 0Dh	-0.65	0101001	29h	-2.05	1000101	45h	-3.45			
								0001110 0Eh	-0.7	0101010	2Ah	-2.1	1000110	46h	-3.5			
						0001111 0Fh	-0.75	0101011	2Bh	-2.15	1000111	47h	-3.55					
				0010000 10h	-0.8	0101100	2Ch	-2.2	1001000	48h	-3.6							
			0010001 11h	-0.85	0101101	2Dh	-2.25	1001001	49h	-3.65								
			0010010 12h	-0.9	0101110	2Eh	-2.3	1001010	4Ah	-3.7								
			0010011 13h	-0.95	0101111	2Fh	-2.35	1001011	4Bh	-3.75								
			0010100 14h	-1	0110000	30h	-2.4	1001100	4Ch	-3.8								
			0010101 15h	-1.05	0110001	31h	-2.45	1001101	4Dh	-3.85								
											0010110 16h	-1.1	0110010	32h	-2.5	1001110	4Eh	-3.9
			0010111 17h	-1.15	0110011	33h	-2.55	1001111	4Fh	-3.95								
			0011000 18h	-1.2	0110100	34h	-2.6	1010000	50h	-4								
			0011001 19h	-1.25	0110101	35h	-2.65	other		-4								
			0011010 1Ah	-1.3	0110110	36h	-2.7											
			0011011 1Bh	-1.35	0110111	37h	-2.75											
striction																		

R82H		Bit												
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code			
VDCS	W	0	1	0	0	0	0	0	1	0	82H			
1 st Parameter	W	1	MTP_VC M	VDCS[6]	VDCS[5]	VDCS [4]	VDCS [3]	VDCS [2]	VDCS [1]	VDCS [0]	00h			

NOTE: "-" Don't care, can be set to VDD or GND level

Description		nmand defines nmand set the ' meter:		C va	alue. Driv	er will ba	ase	on this va	llue for \	/CN	1_DC.			
	Bit	Name					Des	cription						
			VCOM va	llue										
			VCOM[6:0]	Voltage(V)	VCOM[6:0]	Voltage(V)	VCOM[6:0]	Voltage(V)			
			0000000	00h	0(default)	0011100	1Ch	-1.4	0111000	38h	-2.8			
			0000001	0000001 01h -0.05 0011101 1Dh -1.45 0111001 39h -2.85										
			0000010	0000010 02h -0.1 0011110 1Eh -1.5 0111010 3Ah -2.9										



		0000011	03h	-0.15	0011111	1Fh	-1.55	0111011	3Bh	-2.95																
		0000100	04h	-0.2	0100000	20h	-1.6	0111100	3Ch	-3																
		0000101	05h	-0.25	0100001	21h	-1.65	0111101	3Dh	-3.05																
		0000110	06h	-0.3	0100010	22h	-1.7	0111110	3Eh	-3.1																
		0000111	07h	-0.35	0100011	23h	-1.75	0111111	3Fh	-3.15																
		0001000	08h	-0.4	0100100	24h	-1.8	1000000	40h	-3.2																
		0001001	09h	-0.45	0100101	25h	-1.85	1000001	41h	-3.25																
		0001010	0Ah	-0.5	0100110	26h	-1.9	1000010	42h	-3.3																
		0001011	0Bh	-0.55	0100111	27h	-1.95	1000011	43h	-3.35																
		0001100	0Ch	-0.6	0101000	28h	-2	1000100	44h	-3.4																
6-0	VDC616:01	0001101	0Dh	-0.65	0101001	29h	-2.05	1000101	45h	-3.45																
0-0	VDCS[6:0]	VDCS[6.0]	0001110	0Eh	-0.7	0101010	2Ah	-2.1	1000110	46h	-3.5															
		0001111	0Fh	-0.75	0101011	2Bh	-2.15	1000111	47h	-3.55																
		0010000	10h	-0.8	0101100	2Ch	-2.2	1001000	48h	-3.6																
		0010001	11h	-0.85	0101101	2Dh	-2.25	1001001	49h	-3.65																
		0010010	12h	-0.9	0101110	2Eh	-2.3	1001010	4Ah	-3.7																
		0010011	13h	-0.95	0101111	2Fh	-2.35	1001011	4Bh	-3.75																
		0010100	14h	-1	0110000	30h	-2.4	1001100	4Ch	-3.8																
		0010101	15h	-1.05	0110001	31h	-2.45	1001101	4Dh	-3.85																
							0010110	16h	-1.1	0110010	32h	-2.5	1001110	4Eh	-3.9											
																	0010111	17h	-1.15	0110011	33h	-2.55	1001111	4Fh	-3.95	
																0011000	18h	-1.2	0110100	34h	-2.6	1010000	50h	-4		
		0011001	\vdash	-1.25	0110101		-2.65	other		-4																
		0011010		-1.23	0110110		-2.7	Othor		*																
			\vdash																							
		0011011	IBI	-1.35	0110111	3/11	-2.75																			

	7	MTP_VCM	Follow MTP VCOM value in MTP mode O: From the setting of MTP (default) 1:From the setting of register
Restriction			

R83H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PTL	W	0	1	0	0	0	0	0	1	1	83H
1 st Parameter	W	1	-	1	-	-	-	1	HRST[9]	HRST[8]	00h
2 nd Parameter	W	1	HRST[7]	HRST[6]	HRST[5]	HRST[4]	HRST[3]	HRST[2]	-	-	00h
3 rd Parameter	W	1	-	1	-	-	-	1	HRED[9]	HRED[8]	00h
4 th Parameter	W	1	HRED[7]	HRED[6]	HRED[5]	HRED[4]	HRED[3]	HRED[2]	•	-	00h
5 th Parameter	W	1	-	-	-	-	-	-	VRST[9]	VRST[8]	00h
6 th Parameter	W	1	VRST[7]	VRST[6]	VRST[5]	VRST[4]	VRST[3]	VRST[2]	VRST[1]	VRST[0]	00h
7 th Parameter	W	1	-	1	-	-	-	1	VRED[9]	VRED[8]	00h
8 th Parameter	W	1	VRED[7]	VRED[6]	VRED[5]	VRED[4]	VRED[3]	VRED[2]	VRED[1]	VRED[0]	00h
9 th Parameter	W	1	-	-	-	-	-	-	-	PMODE	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description -This command sets partial window.

Name	Description
HRST[9:2]	Horizontal start address
HRED[9:2]	Horizontal end address. HRED must be greater than HRST.
VRST[9:0]	Vertical start address.
VRED[9:0]	Vertical end address. VRED must be greater than VRST.
PMODE	0: disable partial mode(default)
FIVIODE	1: enable partial mode

Note:

No matter HRST[1:0] ,HRST[9:8],HRED[9:8],VRST[9],VRED[9] value being filled, it's always be 00b.

No matter HRED[1:0] value being filled, it's always be 11b.

Gates scan both inside and outside of the partial window.



R90H		Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
PGM	W	0	1	0	0	1	0	0	0	0	90H	

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: After this command is issued, the chip would enter the program mode. The mode would return to standby by hardware reset.
Restriction	

R91H		Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
APG	W	0	1	0	0	1	0	0	0	1	91H	

NOTE: "-" Don't care, can be set to VDD or GND level

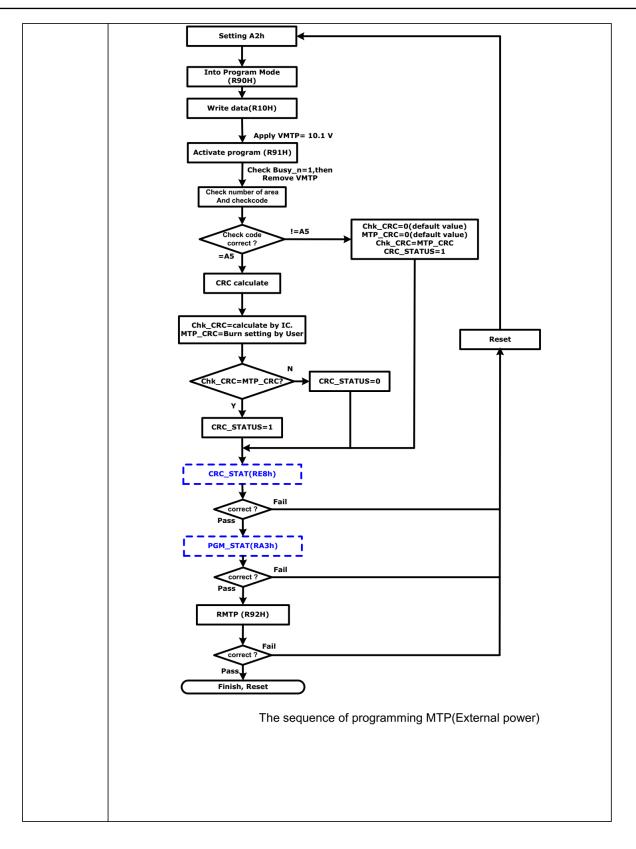
Description	-The command define as follows: After this command is transmitted, the programming state machine would be activated.
Restriction	The BUSY flag would change state from 0 to 1 while the programming is completed.

R92H		Bit										
Inst/Para	R/W	D/CX	D7	D7 D6 D5 D4 D3 D2 D1 D0								
RMTP	W	0	1	0	0	1	0	0	1	0	92H	
1 st Parameter	R	1				Dur	nmy				-	
2 nd Parameter	R	1	The data of address 0x000 in the MTP									
3 rd Parameter	R	1		The data of address 0x001 in the MTP								
4 th Parameter	R	1		:								
5 th Parameter	R	1		The data of address (n-1) in the MTP								
6 th ~(m-1) th Parameter	R	1										
m th Parameter	R	1			The d	ata of addre	ess (n) in th	e MTP			-	

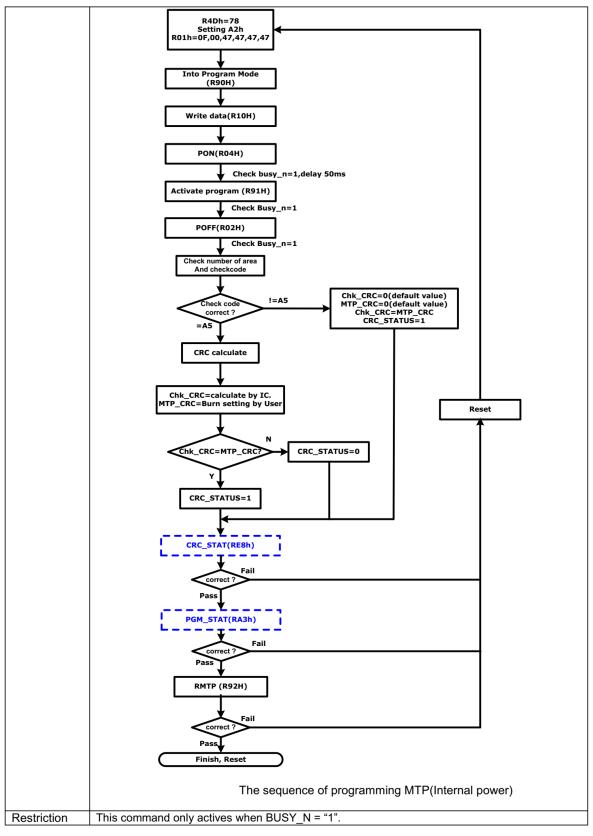
NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows:
	The command is used for reading the content of MTP for checking the data of programming.
	The value of (n) is depending on the amount of programmed data, the max address = 0x17FF









R9EH		Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
REV2	W	0	1	0	0	1	1	1	1	0	9EH	
1 st Parameter	R	1	0	0	0	0	0	0	0	1	01h	



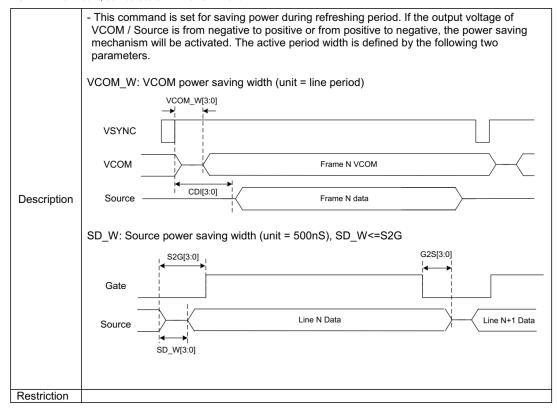
	-The comma	nd defines as:	
Description	Bit	Description	
	7-0	CHIP_REV	
			1
Restriction			

R9FH		Bit												
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code			
RMRB	W	0	1	0	0	1	1	1	1	1	9FH			
1 st Parameter	R	1		Dummy										
2 nd Parameter	R	1		The data of address 0x16F7 in the MTP										
3 rd Parameter	R	1		:										
:	R	1		:										
97 th Parameter	R	1				1	:				00h			
98 th Parameter	R	1		:										
101 th Parameter	R	1		The data of address 0x175A in the MTP										

Description	-The command define as follows: The command is used for reading the content of MTP Reserved Byte for checking the data of programming. This command could read these information from MTP directly.
Restriction	

RE3H		Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code	
PWS	W	0	1	1	1	0	0	0	1	1	E3H	
1 st Parameter	W	1		VCOM	_W[3:0]			00h				

NOTE: "-" Don't care, can be set to VDD or GND level





RE4H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
LVSEL	W	0	1	1	1	0	0	1	0	0	E4H
1 st Parameter	W	1	1	-	1	-	-	ı	LVD_SEL[1:0]		03h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	LVD_SEL[1:0]: Low Power V	oltage Selection	
	LVD_SEL[1:0]	LVD value	
	00	< 2.2 V	
	01	< 2.3 V	
	10	< 2.4 V	
	11	< 2.5 V (default)	
Restriction			



8. Handling, Safety and Environment Requirements

Warning

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

Caution

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components. Disassembling the display module.

Disassembling the display module can cause permanent damage and invalidates the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status					
Product specification	This data sheet contains final product specifications.				
	Limiting values				

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC

134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.



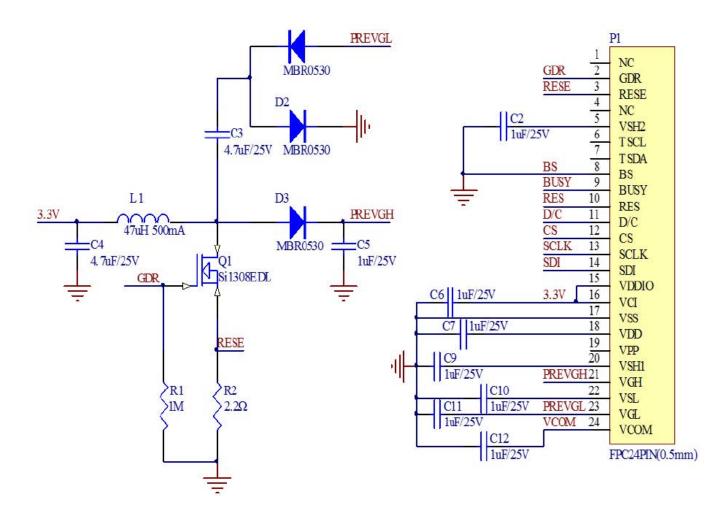
9. Reliability test

NO	Test items	Test condition
1	Low-Temperature Storage	T = -25 °C, 240 h Test in white pattern
2	High-Temperature Storage	T=60°C, RH=35%, 240h Test in white pattern
3	High-Temperature Operation	T=40°C, RH=35%, 240h
4	Low-Temperature Operation	0°С, 240h
5	High-Temperature, High-Humidity Operation	T=40°C, RH=80%, 240h
6	High Temperature, High Humidity Storage	T=50°C, RH=90%, 240h Test in white pattern
7	Temperature Cycle	1 cycle:[-25°C 30min]→[+60°C 30 min]: 50 cycles Test in white pattern
8	UV exposure Resistance	765W/m ²for 168hrs,40 ℃ Test in white pattern
9	ESD Gun	Air+/-15KV;Contact+/-8KV (Test finished product shell, not display only) Air+/-8KV;Contact+/-6KV (Naked EPD display, no including IC and FPC area) Air+/-4KV;Contact+/-2KV (Naked EPD display, including IC and FPC area)

Note: Put in normal temperature for 1hour after test finished, display performance is ok.



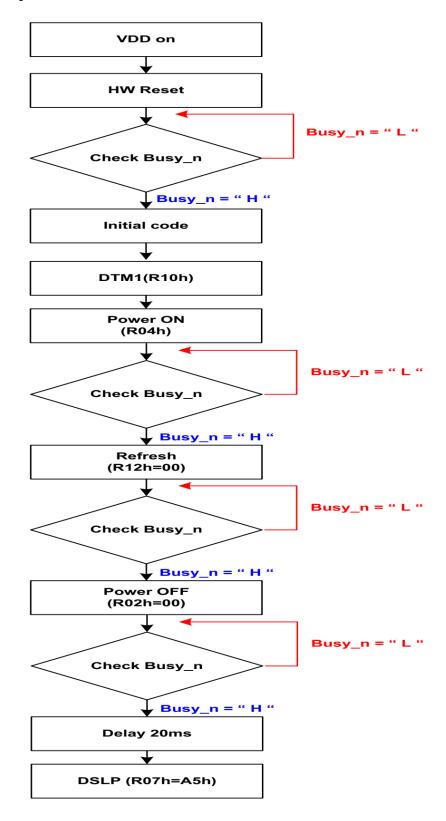
10. Typical Application Circuit





11. Typical Operating Sequence

11.1 Normal Operation Flow

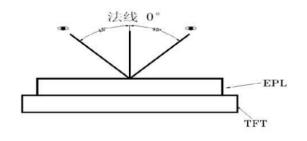




12. Inspection method and condition

12. 1 Inspection condition

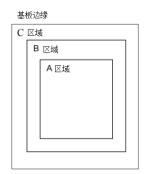
Item	Condition
Illuminance	800~1500 lux
Temperature	22°C ±3°C
Humidity	55±10 %RH
Distance	≥30cm
Angle	Vertical fore and aft 45
Inspection method	By eyes



12. 2 Zone definition

A Zone: Active area B Zone: Border zone

C Zone: From B zone edge to panel edge





12. 3 General inspection standards for products 12.3.1 Appearance inspection standard

Inspection	on item	Figure		A zone inspection standard	B/C zone	Inspection method	MAJ/ MIN
st form	Spot defects uch as dot, oreign natter, air pubble, and lent etc.	Diameter D=(L+W)/2 (L-length, W-width) Measuring method shown in the figure below D=(L+W)/2	The distance between the two spots should not be less than 10mm	$\begin{array}{llllllllllllllllllllllllllllllllllll$	Foreign matter D≤1mm Pass	Check by eyes Film gauge	MIN

Inspection item		Figure		A zone inspection standard	B/C zone	Inspection method	MA J/ MI N
Line defects	Line defects such as scratch, hair etc.	L-Length, W-Width, (W/L)<1/4 Judged by line, (W/L)≥1/4 Judged by dot	The distance between the two lines should not be less than 5mm	7.5"-13.3"Module (Not include 7.5"): L>10mm,N=0 W>0.8mm, N=0 5mm≤L≤10mm, 0.5mm≤W≤0.8mm N≤2 L≤5mm, W≤0.5mm Ignore 4.2"-7.5"Module (Not include 4.2"): L>8mm,N=0 W>0.2mm, N=0 2mm≤L≤8mm, 0.1mm≤W≤0.2mm N≤4 L≤2mm, W≤0.1mm Ignore Module below 4.2": L>5mm,N=0 W>0.2mm, N=0 2mm≤L≤5mm, 0.1mm≤W≤0.2mm N≤4 L≤2mm, W≤0.1mm Ignore	Ignore	Check by eyes Film gauge	MIN

Inspection item Figure		Figure	Inspection standard	Inspection method	MA J/ MIN
Panel chipping and crack defects	TFT panel chipping	X the length, Y the width, Z the chipping height, T the thickness of the panel	Chipping at the edge: Module over 7.5" (Include 7.5"): $X \le 6mm, Y \le 1mm$ $Z \le T$ $N = 3$ Allowed Module below 7.5" (Not include 7.5"): $X \le 3mm, Y \le 1mm$ $Z \le T$ $N = 3$ Allowed Chipping on the corner: IC side $X \le 2mm$ $Y \le 2mm$, Non-IC side $X \le 1mm$ $Y \le 1mm$. Allowed Note: Chipping should not damage the edge wiring. If it does not affect the display, allowed	Check by eyes. Film gauge	MIN
	Crack	玻璃裂紋	Crack at any zone of glass, Not allowed	Check by eyes. Film gauge	MIN
	Burr edge	1	No exceed the positive and negative deviation of the outline dimensions $X+Y \le 0.2 mm$ Allowed	Calliper	MIN
	Curl of panel	H Curl height	Curl height H≤Total panel length 1% Allowed	Check by eyes	MIN



				Inspecti	MAJ
Inspec	tion item	Figure	Inspection standard	on	/
				method	MIN
PS defect	Water proof film		Waterproof film damage, wrinkled, open edge, not allowed Exceeding the edge of module(according to the lamination drawing) Not allowed Edge warped exceeds height of technical file, not allowed	Check by eyes	MIN
			Adhesive height exceeds the display surface, not allowed		
RTV defect	Adhesive effect		1. Overflow, exceeds the panel side edge, affecting the size, not allowed 2. No adhesive at panel edge≤1mm, mo exposure of wiring, allowed 3. No adhesive at edge and corner1*1mm, no exposure of wiring, allowed	Check by eyes	MIN
			Protection adhesive, coverage width within W≤1.5mm, no break of adhesive, allowed		
	Adhesive re-fill		Dispensing is uniform, without obvious concave and breaking, bubbling and swell, not higher than the upper surface of the PS, and the diameter of the adhesive re-filling is not more than 8mm, allowed	Check by eyes	MIN
EC defect	Adhesive bubble	防水胶涂布区 封边胶边缘 PS边缘 Border外缘(PPL边缘)	 Effective edge sealing area of hot melt products ≥1/2 edge sealing area; Bubble a+b≥1/2 effective width, N≤3, spacing≥5mm, allowed No exposure of wiring, allowed 	Check by eyes	MIN

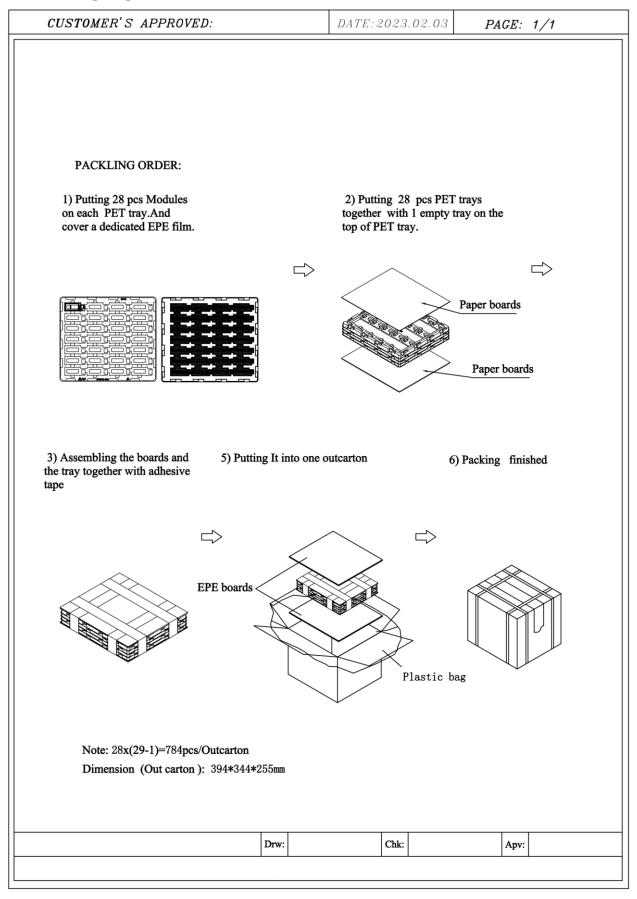
Inspecti	ion item	Figure	Inspection standard	Inspection method	MAJ/ MIN
EC defect	Adhesive effect	OK OK	1. Overflow, exceeds the panel side edge, affecting the size, not allowed 2.No adhesive at panel edge≤1mm, mo exposure of wiring, allowed 3.No adhesive at edge and corner 1*1mm, no exposure of wiring, allowed 4. Adhesive height exceeds the display surface, not allowed	Visual, caliper	MIN
Silver dot adhesive	Silver dot adhesive		1. Single silver dot dispensing amount ≥1mm, allowed 2. One of the double silver dot dispensing amount is ≥1mm and the other has adhesive (no reference to 1mm) Allowed	Visual	MIN
defect			Silver dot dispensing residue on the panel ≤0.2mm, allowed	Film gauge	MIN
	FPC wiring		FPC, TCP damage / gold finger peroxidation, adhesive residue, not allowed	Visual	MIJ
FPC defect	FPC golden finger		The height of burr edge of TCP punching surface ≥ 0.4mm, not allowed	Caliper	MIN
	FPC damage/cr ease		Damage and breaking, not allowed Crease does not affect the electrical performance display, allowed	Check by eyes	MIN



Inspection	on item	Figure Inspection standard		Inspection method	MAJ/ MIN
Protective Protective		Scratch and crease on the surface but no affe	ct to protection function, allowed	Check by eyes	MIN
film defect	film	Adhesive at edge L≤5mm, W≤0.5mm, N=	2, no entering into viewing area	Check by eyes	MIN
Stain defect	Stain	If stain can be normally wiped clean by > 99% alcohol, allowed		Visual	MIN
Pull tab defect	Pull tab	The position and direction meet the document requirements, and ensure that the protective film can be pulled off.		Check by eyes/ Manual pulling	MIN
Shading tape defect	Shading tape	Tilt≤10°, flat without warping, completely covering the IC.		Check by eyes/ Film gauge	MIN
Stiffener	Stiffener	Flat without warping, Exceeding the left and right edges of the FPC is not allowed. Left and right can be less than 0.5mm from FPC edge		Check by eyes	MIN
Label	Label/ Spraying code	The content meets the requirements of the w requirements of the technical documents.	ork sheet. The attaching position meets the	Check by eyes	MIN



13. Packaging





14. Precautions

- (1) Do not apply pressure to the EPD panel in order to prevent damaging it.
- (2) Do not connect or disconnect the interface connector while the EPD panel is in operation.
- (3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.
- (4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.
- (5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as "Ghosting" or "Image Sticking" may occur. It is recommended to refreshed the ESL /EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL / EPD Tag with a completely white image to avoid this issue
- (6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.